

International **IOR** Rectifier

HFA08SD60SPbF

Ultrafast, Soft Recovery Diode

Features

- Ultrafast Recovery Time
- Ultrasoft Recovery
- Very Low I_{RRM}
- Very Low Q_{rr}
- Guaranteed Avalanche
- Specified at Operating Temperature
- Lead-Free

Benefits

- Reduced RFI and EMI
- Reduced Power Loss in Diode and Switching Transistor
- Higher Frequency Operation
- Reduced Snubbing
- Reduced Parts Count

Description/ Applications

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for freewheeling, flyback, power converters, motor drives, and other applications where high speed and reduced switching losses are design requirements.

$$t_{rr} = 18\text{ns}$$

$$I_{F(AV)} = 8\text{Amp}$$

$$V_R = 600\text{V}$$

Package Outline



Absolute Maximum Ratings

Parameters	Max	Units
V_{RRM} Cathode-to-Anode Voltage	600	V
$I_{F(AV)}$ Continuous Forward Current $T_C = 100^\circ\text{C}$	8	A
I_{FSM} Single Pulse Forward Current	60	
I_{FRM} Peak Repetitive Forward Current	24	
P_D Maximum Power Dissipation $T_C = 100^\circ\text{C}$	14	W
T_J, T_{STG} Operating Junction and Storage Temperatures	- 55 to 150	$^\circ\text{C}$

10/30/06

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameters	Min	Typ	Max	Units	Test Conditions
V_{BR} , V_R Breakdown Voltage, Blocking Voltage	600	-	-	V	$I_R = 100\mu\text{A}$
V_F Forward Voltage See Fig. 1	-	1.4	1.7	V	$I_F = 8\text{A}$
	-	1.7	2.1	V	$I_F = 16\text{A}$
	-	1.4	1.7	V	$I_F = 8\text{A}$, $T_J = 125^\circ\text{C}$
I_R Max. Reverse Leakage Current	-	0.3	5.0	μA	$V_R = V_R$ Rated
	-	100	500	μA	$T_J = 125^\circ\text{C}$, $V_R = 0.8 \times V_R$ Rated
C_T Junction Capacitance	-	10	25	pF	$V_R = 200\text{V}$
L_S Series Inductance	-	8.0	-	nH	Measured lead to lead 5mm from package body

Dynamic Recovery Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameters	Min	Typ	Max	Units	Test Conditions
t_{rr} Reverse Recovery Time	-	18	-	ns	$I_F = 1.0\text{A}$, $di_F/dt = 200\text{A}/\mu\text{A}$, $V_R = 30\text{V}$
	-	37	55		$T_J = 25^\circ\text{C}$
	-	55	90		$T_J = 125^\circ\text{C}$
I_{RRM} Peak Recovery Current	-	3.5	5.0	A	$T_J = 25^\circ\text{C}$
	-	4.5	8.0		$T_J = 125^\circ\text{C}$
Q_{rr} Reverse Recovery Charge	-	65	138	nC	$T_J = 25^\circ\text{C}$
	-	124	360		$T_J = 125^\circ\text{C}$
$di_{(rec)}/dt$ Rate of Fall of recovery Current	-	240	-	A/ μs	$T_J = 25^\circ\text{C}$
	-	210	-		$T_J = 125^\circ\text{C}$

Thermal - Mechanical Characteristics

Parameters	Min	Typ	Max	Units
T_J Max. Junction Temperature Range	-	-	- 55 to 150	$^\circ\text{C}$
T_{Stg} Max. Storage Temperature Range	-	-	- 55 to 150	
T_{lead} Lead Temperature	-	-	300	
R_{thJC} Thermal Resistance, Junction to Case	-	-	3.5	$^\circ\text{C}/\text{W}$
R_{thJA} ① Thermal Resistance, Junction to Ambient	-	-	80	
Wt Weight	-	2.0	-	g
	-	0.07	-	(oz)

① Typical Socket Mount

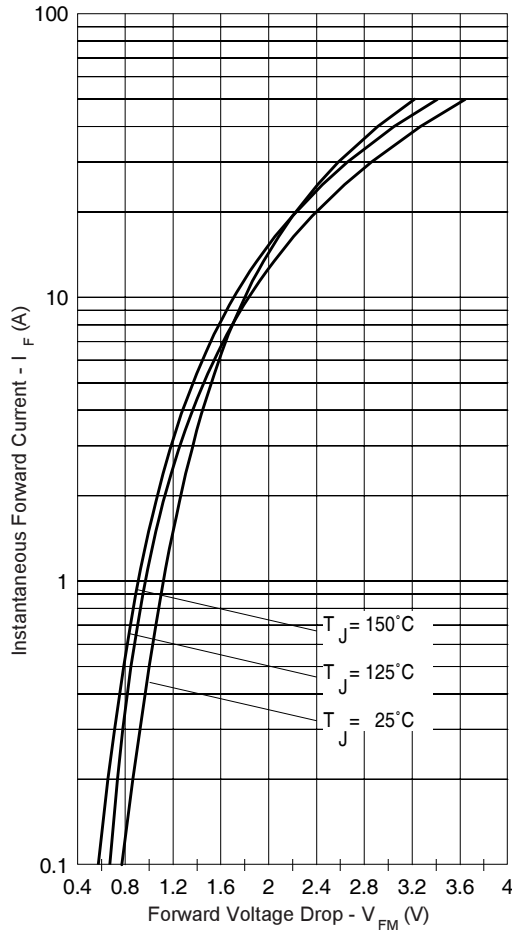


Fig. 1 - Typical Forward Voltage Drop Characteristics

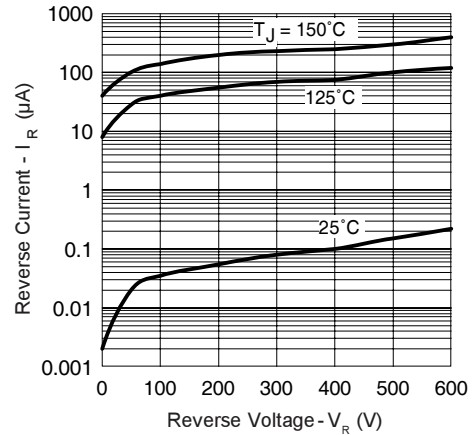


Fig. 2 - Typical Values Of Reverse Current Vs. Reverse Voltage

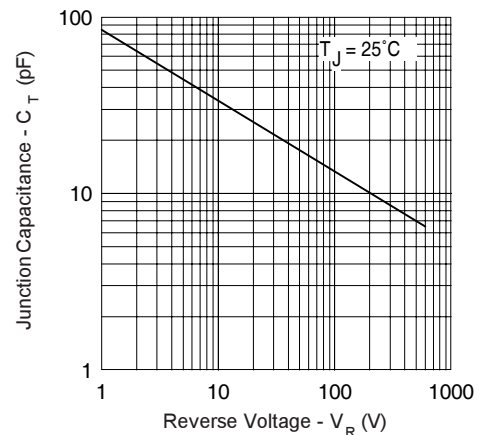


Fig. 3 - Typical Junction Capacitance Vs. Reverse Voltage

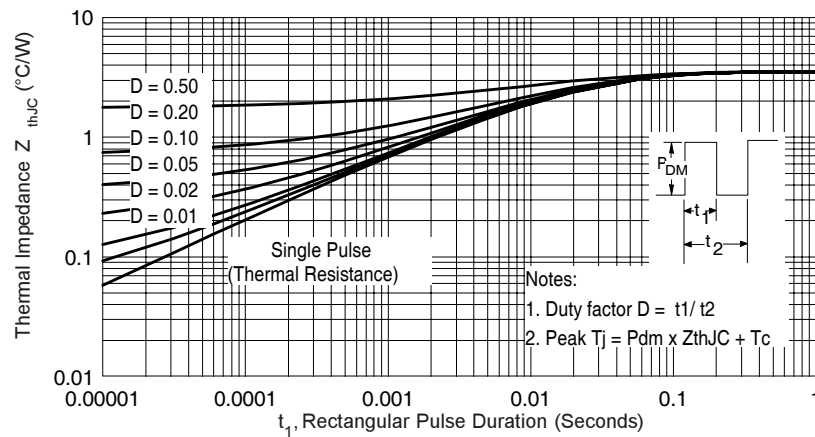
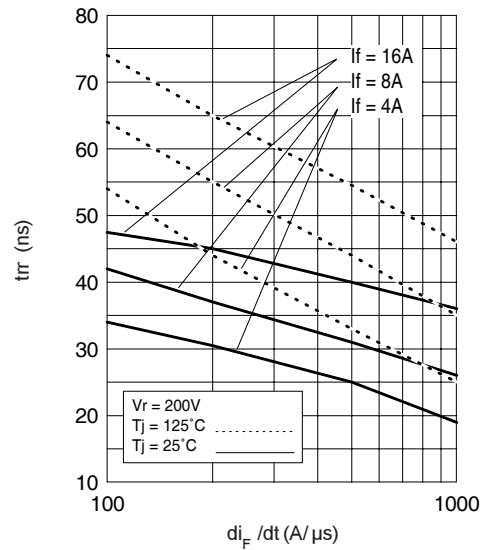
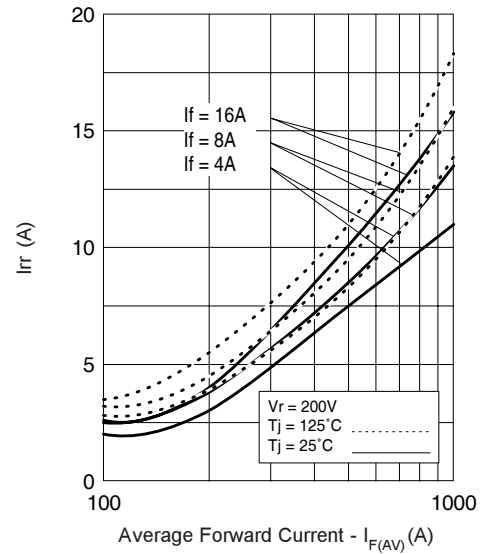
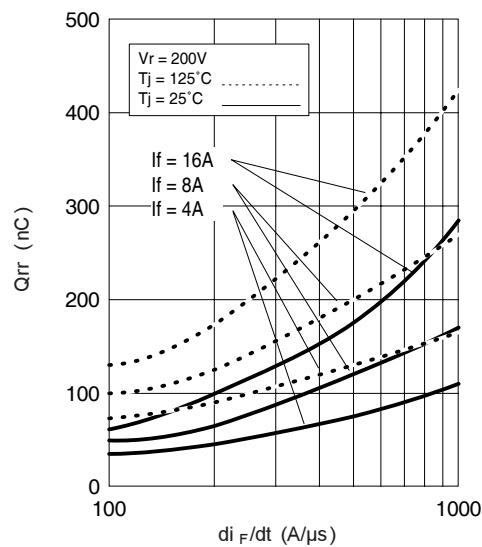
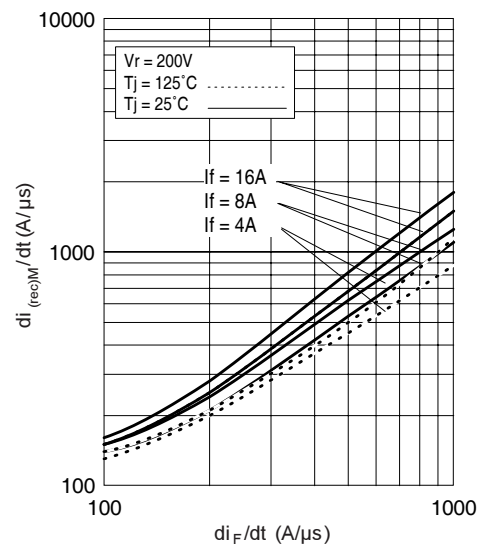


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

Fig. 5 - Typical Reverse Recovery vs. di_F/dt Fig. 6 - Typical Recovery Current vs. di_F/dt Fig. 7 - Typical Stored Charge vs. di_F/dt Fig. 8 - Typical $di_{(rec)M}/dt$ vs. di_F/dt

Reverse Recovery Circuit

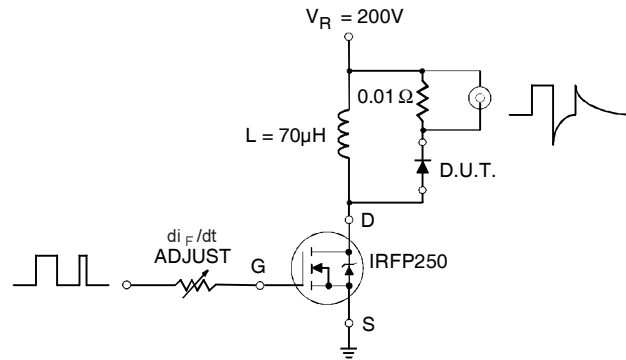
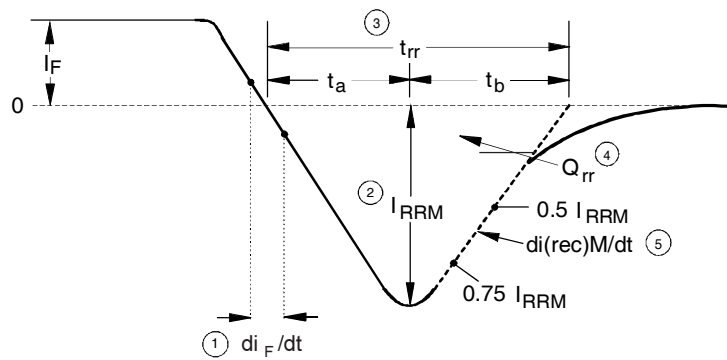


Fig. 9- Reverse Recovery Parameter Test Circuit



1. di_F/dt - Rate of change of current through zero crossing

2. I_{RRM} - Peak reverse recovery current

3. t_{rr} - Reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current

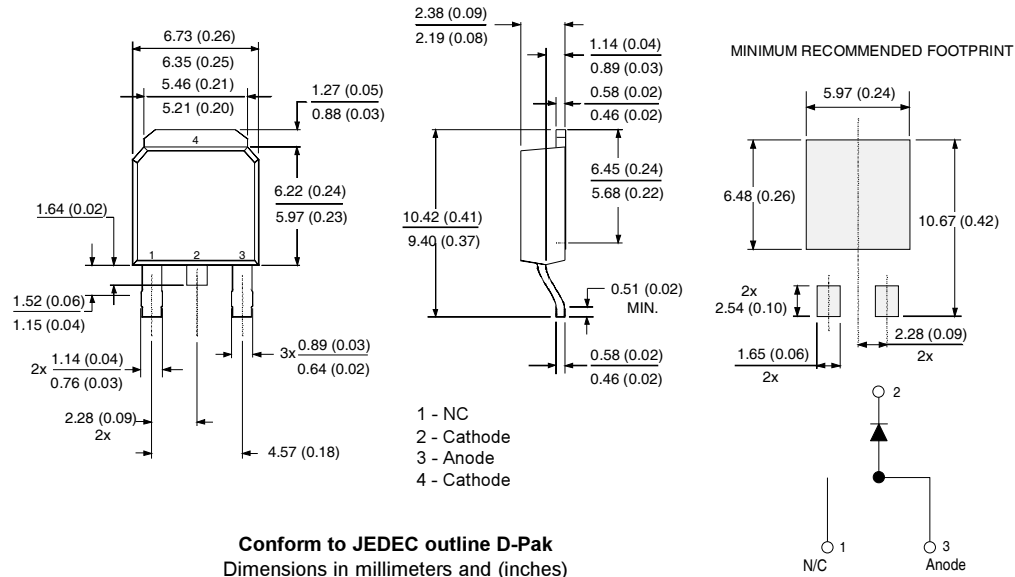
4. Q_{rr} - Area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

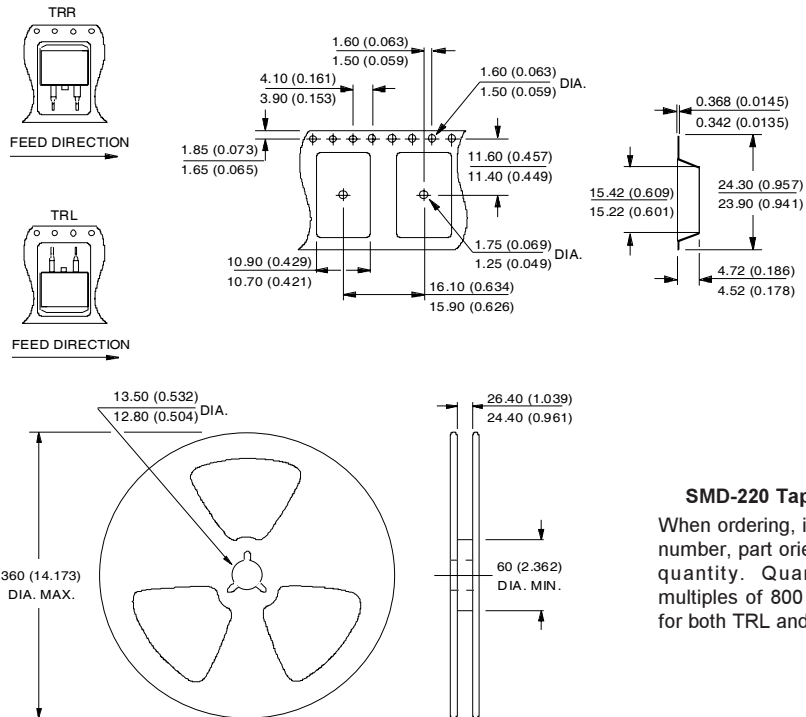
5. $di_{(rec)M}/dt$ - Peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

Outline Table



Tape & Reel Information

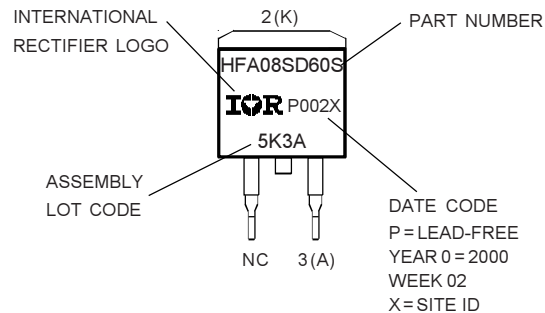


SMD-220 Tape & Reel

When ordering, indicate the part number, part orientation and the quantity. Quantities are in multiples of 800 pieces per reel for both TRL and TRR.

Marking Information

EXAMPLE: THIS IS AN HFA08SD60S



Ordering Information Table

Device Code

HF	A	08	SD	60	S
1	2	3	4	5	6

- 1** - Hexfred Family
- 2** - Electron Irradiated
- 3** - Current Rating (08 = 8A)
- 4** - D-PAK
- 5** - Voltage Rating (60 = 600V)
- 6** - Suffix

S = D²PAK/ Dpak
 TR = Tape & Reel
 TRL = Tape & Reel Left
 TRR = Tape & Reel Right

Note: "PbF" suffix at the end of the part number indicates Lead-Free.

Data and specifications subject to change without notice.
 This product has been designed and qualified for Consumer Level.
 Qualification Standards can be found on IR's Web site.



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